

VERSION SHOWING THE CHANGES TO THE ABSTRACT

IN THE ABSTRACT

Amend the abstract as follows:

~~The present invention relates to a method and a device for patterning organic layers. A first aspect of the invention provides a method for patterning an unpatterned organic layer. The method is advantageously suitable for patterning an insulator layer of organic circuits. Patterning means at a predetermined temperature are pressed at a predetermined pressure (a compression pressure) into the organic layer. The pressing in operation is suitable for permanently patterning the organic layer using the patterning means.~~

~~A further aspect of the invention provides a device for patterning organic layers. The device according to the invention is suitable in particular for patterning organic insulator layers of organic circuits. For this purpose, the device has patterning means having predetermined dimensions. Said patterning means can be pressed at a predetermined temperature and at a predetermined pressure into the organic layer. By pressing the patterning means into the organic layer, the latter is permanently patterned.~~

An unpatterned organic layer, which may be an insulator layer of an organic circuit, is patterned with a patterning arrangement, which preferably comprises a device,

which patterns the layer at a predetermined temperature and at a predetermined pressure (a compression pressure) into the organic layer. The applying operation permanently patterns the organic layer with the patterning arrangement. The device has patterns of predetermined dimensions. The patterning arrangement displaces the contact region of the organic layer displacing the contact region to form permanent open regions comprising depressions and/or holes corresponding to the dimensions of the pattern arrangement and which may be utilized as plated through holes.